

ABSTRACT

Disclosed is a temporary protective film for semiconductor encapsulation molding, the temporary protective film including a support film, an adhesive layer provided on one surface of the support film, and a non-adhesive layer provided on a surface of the support film on an opposite side from a surface provided with the adhesive layer. The thickness of the non-adhesive layer is 10 μm or less. A surface of the non-adhesive layer on an opposite side of a surface in contact with the support film, has a surface roughness Ra of 0.1 μm or more.

Fig. 1